



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-08-30
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	LAURENT TOSI	Representative Title	MMS MD CHAMPION
Representative Phone *	33 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F722RET6	B05W*452ESXA	A	9988	2016-08-30
	Amount	UoM	Unit type	ST ECOPACK Grade
	387.827	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10X10X1.4	64	L bend	
Comment	Package: LQFP 64L 10x10x1.4 64L			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	B05W*452ESXA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	19.379	mg	supplier	die	Silicon (Si)	7440-21-3		18.391	mg	949017	47421
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.068	mg	3509	175
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.443	mg	22860	1142
die (s)				supplier	metallization	Tantalum (Ta)	7440-25-7		0.075	mg	3870	193
die (s)				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	52	3
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.199	mg	10269	513
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.052	mg	2683	134
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.150	mg	7740	387
Die Attach(ABLEBOND 3230)	Other inorganic materials	1.161	mg	supplier	Glue	Silver	7440-22-4		0.854	mg	735573	2202
Die Attach(ABLEBOND 3230)				supplier	Glue	Highly cross-linked polymer	Proprietary		0.307	mg	264427	792
Encapsulation(EME-G700E_Sumitomo)	Other inorganic materials	235.655	mg	supplier	Mold Compound	Epoxy Resin	Proprietary		18.903	mg	80215	48741
Encapsulation(EME-G700E_Sumitomo)				supplier	Mold Compound	Phenol Resin	Proprietary		12.602	mg	53476	32494
Encapsulation(EME-G700E_Sumitomo)				supplier	Mold Compound	Carbon Black	1333-86-4		0.756	mg	3208	1949
Encapsulation(EME-G700E_Sumitomo)				supplier	Mold Compound	Silica Fused	60676-86-0		203.394	mg	863101	524445
Bonding wire(Au_HA3_HERAUS)	Other inorganic materials	1.252	mg	supplier	wire	Gold	7440-57-5		1.252	mg	1000000	3228
Finishing(Pure Tin_Nuonengda)	Other inorganic materials	1.436	mg	supplier	Connection coating	Tin	7440-31-5		1.436	mg	1000000	3703
Leadframe(Mitsui C194+AG)	Other inorganic materials	128.944	mg	supplier	Alloy	Copper	7440-50-8		122.749	mg	951955	316504
Leadframe(Mitsui C194+AG)				supplier	Alloy	Iron	12597-68-1		2.939	mg	22793	7578
Leadframe(Mitsui C194+AG)				supplier	Alloy	Lead	7439-92-1		0.000	mg	1	0
Leadframe(Mitsui C194+AG)				supplier	Alloy	Phosphorus	7723-14-0		0.032	mg	248	83
Leadframe(Mitsui C194+AG)				supplier	Alloy	Zinc	7440-66-6		0.162	mg	1256	418
Leadframe(Mitsui C194+AG)				supplier	Alloy	Silver	7440-22-4		3.062	mg	23747	7895